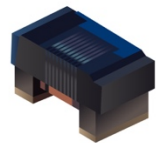


# MATERIAL DECLARATION SHEET

Material Number	CWF1610 Series			
Product Line	Chip Inductor			
Compliance Date	2020/02/18			
RoHS Compliant	Yes	MSL	Level 1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ferrite body	Ferrite Ni-Zn Series	0.0038	Iron oxide	1309-37-1	62.000	47.120	76.00
				Nickel oxide	1313-99-1	11.000	8.360	
				Zinc oxide	1314-13-2	20.000	15.200	
				Copper oxide	1317-38-0	7.000	5.320	
2	Copper/ Coating	Copper Wire	0.0006	Copper	7440-50-8	100.000	12.000	15.00
		Copper Colored Coating On The Magnet Wire_SFHW	0.00015	Polyurethane Resin	26680-22-8	100.000	3.000	
3	Terminal	Silver paste_DP4303W	0.00015	Silver	7440-22-4	73.68	2.21	3.00
				Silicon dioxide	60676-86-0	15.79	0.474	
				Resins	9004-57-3	10.53	0.316	
4	Solder Base	S Nickel Pellets	0.00005	Nickel	7440-02-0	100.000	1.000	1.00
5	Solder	Lead Free Solder	0.00005	Tin	7440-31-5	100.000	1.000	1.00
6	Back Membrane	Adhesive	0.0002	Diacylate compound	42978-66-5	88.000	3.52	4.00
				Silicon dioxide	14808-60-7	12.000	0.48	
Total weight			0.005					

**This Document was updated on: 2020/02/18**

**Important remarks:**

1. It is the responsibility of the user to verify they are accessing the latest version.